



AP450GX & AR450GX MP Server System

Monthly Change Summary

In order to facilitate the conversion process and proactively communicate changes to customers, Intel is publishing this monthly change summary.



April 1998 Edition

Enterprise Server Group

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SECTION 1: PRODUCT INDEX**450GX Based Products:**

Product Family	Product Type	Product
AP450GX	Board Set/Baseboard	PALBBRDC
AP450GX	System	ALC0MB2CPMC
AP450GX	System	ALPCD200512C
AP450GX	System	ALPCD2001MC
AR450GX	System	ALRK0MB2CPMC
AR450GX	System	ALRK128M2X512
AP450GX	Processor Modules	PALCPA0X
AP450GX	Processor Modules	PALCPA1X200512
AP450GX	Processor Modules	PALCPA2X200512
AP450GX	Processor Modules	PALCPA2X2001M
AP450GX	Memory Modules	PALMEM1GBM0
AP450GX	Memory Modules	ALMEM4GBM0
AP450GX	Other Modules	PALTRMBRD
AP450GX	Accessories	PPS420WHS
AR450GX	Accessories	ALRKPS625W
AP450GX	Accessories	ALCPUUPKIT
AP450GX	Accessories	ALFSINKKIT
AP450GX	Accessories	POCAHDDCARIER
AP450GX	Accessories	PPS420WHS
AP450GX	Accessories	ALPCPADHDDCAR
AP450GX	Accessories	POCAFRONPNL
AP450GX	Accessories	POCASCSIBP
AP450GX	Accessories	POCALEDBD

SECTION 2: CHANGES FROM PREVIOUS EDITION**2.1 Revisions to existing changes:**

Change Notification #	Title	Type/Class	Reason
5555849	Modification to Video DRAM and Upgrade of BIOS	1	Changed First availability of Post-Conversion Material from January 1998 to February 1998
5555845	Add Protection Circuitry to the 1MB Processor Module	1	Changed First availability of Post-Conversion Material from January 1998 to February 1998
5546546	Change t System Spatter Coat Paint	2	For some product codes: changed First availability of Post-Conversion Material from February 1998 to June 1998
5561008	System Upgrade Hot Swap Backplane to Firmware Version 2.11	2	Changed First availability of Post-Conversion Material from February 1998 to June 1998
5571061	Various Rack System Components and Boards	1	Changed First availability of Post-Conversion Material from March 1998 to April 1998

2.2 Changes added since last edition:

Change Notification #	Title	Type/Class	Reason

2.3 Changes removed since last edition:

Change Notification #	Title	Type/Class	Reason
5563218	Board Upgrade Hot Swap Backplane to Firmware Version 2.11	2	Change was implemented and was reported for two additional months
5550981	Updating System to TEAC 8xxx Series Floppy and BIOS 14	1	Change was implemented and was reported for two additional months
5560567	Incorporate More Reliable Power Distribution Backplane into Remaining Systems	2	Change was implemented and was reported for two additional months

SECTION 3: KEY CHANGE SUMMARY

3.1 AP450GX MP Server Board Set

3.1.1 Baseboard Related Changes

Change Notification #: 5555849

Change Title: Modification to Video DRAM and Upgrade of BIOS

Type of Notification: Class 1 Form/Fit/Function Notification

Key Characteristics of the Change:

Product Material

Product Design

Software

Forecasted Key Milestones:

Date of First Availability of Post-Conversion Material: February 1998

Description of Change to the Customer: The BIOS will be upgraded to version 1.00.14 CD0. The socket for the second video DRAM will be removed and replaced with a second 512KB video DRAM, increasing the total video DRAM to 1MB. This will also improve the manufacturability of the board.

Customer Impact of Change and Recommended Action: None. The BIOS 1.00.14 CD0 software package is available for download on Intel's public site: http://developer.intel.com/design/servers/AP450GX/docs/bios_14.exe

Products Affected / Intel's Ordering Codes:

Affected Product Code	Pre-conversion AA #	Post-conversion AA #	Pre-conversion PBA #	Post-Conversion PBA #
ALBBRDC	663622-008	663622-009	666107-108	666107-109
ALBBRD CD	674729-009	674729-010	666107-108	666107-109
ALBBRDCT	689607-008	689607-009	689606-108	689606-109
MFG666107I	696004-001	696004-002	666107-108	666107-109

3.1.2 Processor Module Related Changes

Change Notification #: 5555845

Change Title: Add Protection Circuitry to the 1MB Processor Module

Type of Notification: Class 1 Form/Fit/Function Notification

Key Characteristics of the Change:

Product Design

Forecasted Key Milestones:

Samples Availability Dates:

December 1997

Customer Qualification Deadline:

January 1998

Customer Ready to Receive Post-Conversion Material Deadline:

January 1998

Date of First Availability of Post-Conversion Material:

February 1998

Description of Change to the Customer: To improve failsafe conditions for passive components, a protective circuitry will be added to the 1MB processor module to actively monitor device operating conditions.

Customer Impact of Change and Recommended Action: Optional. Test plans and reports are available for the protective circuitry change: Intel Customer Support (1-800-628-8686), or your Intel Sales Representative.

Products Affected / Intel's Ordering Codes:

Affected Product Code	Pre-conversion AA #	Post-conversion AA #	Pre-conversion PBA #	Post-Conversion PBA #
ALCPA0X	670438-004	670438-005	656631-226	656631-303
ALCPA0XD	689881-004	689881-005	689882-226	689882-303
ALCPA1X200512	663174-007	663174-008	656631-226	656631-303
ALCPA2X2001M	676798-002	676798-003	656631-226	656631-303
ALCPA2X200512	651662-007	651662-008	656631-226	656631-303
MFG656631I	686776-001	686776-002	656631-226	656631-303

3.2 AP450GX MP Floor Standing Server System

3.2.1 Chassis Related Changes

Change Notification #: 5546546

Change Title: Change to System Spatter Coat Paint

Type of Notification: Class 2 Form/Fit/Function Notification

Key Characteristics of the Change:

Product Material

Forecasted Key Milestones:

Date of First Availability of Post-Conversion Material: see below

Description of Change to the Customer: To improve manufacturing yield the paint process for covers will be changed from self-texturing to spatter coat. This conversion was noted as canceled in the Monthly Conversion Summary for December 1997, but has been reopened due to an increased availability of materials.

Customer Impact of Change and Recommended Action: None.

Products Affected / Intel's Ordering Codes:

Date of First Availability of Post-Conversion Material: December 1997

86505M0

86506MM

SERVERHX

Date of First Availability of Post-Conversion Material: June 1998

ALPC0MB2CPMC

ALPCD2001MC

ALPCD200512C

ALPCD200512C0F

Change Notification #: 5546548

Change Title: Pre-Folded System Cables

Type of Notification: Class 2 Form/Fit/Function Notification

Key Characteristics of the Change:

Product Material

Forecasted Key Milestones:

Date of First Availability of Post-Conversion Material: February 1998

Description of Change to the Customer: The design of various system cables will be modified to contain pre-folding in order to fit the system routing requirements.

Customer Impact of Change and Recommended Action: None.

Products Affected / Intel's Ordering Codes:

86505M0

86506MM

ALPC0MB2CPMC

ALPCD2001MC

ALPCD200512C

ALPCD200512C0F

SERVERHX

Change Notification #: 5560550

Change Title: Enhanced System Fan With Low-Speed Rotor Notification Capabilities

Type of Notification: Class 2 Form/Fit/Function Notification

Key Characteristics of the Change:

Product Material

Forecasted Key Milestones:

Date of First Availability of Post-Conversion Material: January 1998

Description of Change to the Customer: Introduction of a new system fan (#693043-001) to improve notification of fan failures. The new fan has the ability to report both low-speed and fan-stop conditions.

Customer Impact of Change and Recommended Action: None.

Products Affected / Intel's Ordering Codes:

86505M0

86506MM

ALPC0MB2CPMC

ALPCD2001MC

ALPCD200512C

ALPCD200512C0F

SERVERHX

Change Notification #: 5559833

Change Title: System Incorporation of 1MB Protective Circuitry, Video Memory Upgrade and New SCSI Cabling.

Type of Notification: Class 1 Form/Fit/Function Notification

Key Characteristics of the Change:

Product Material

Product Design

Forecasted Key Milestones:

Date of First Availability of Post-Conversion Material: February 1998

Description of Change to the Customer: Add protective circuitry to the 1MB processor module, see conversion notification #5555845 for more information. Modification to the video DRAM, see conversion notification #5555849 for more information. Update ultra SCSI cables to improve signal margin of the SCSI system.

Customer Impact of Change and Recommended Action: None. Test plans and reports are available for the protective circuitry change: Intel Customer Support (1-800-628-8686), or your Intel Sales Representative.

Products Affected / Intel's Ordering Codes:

86505M0

86506MM

ALPC0MB2CPMC

ALPCD2001MC

ALPCD200512C

ALPCD200512C0F

ALRK0MB2CPMC

ALRK128M2X512

SERVERHX

3.2.2 Other Changes

Change Notification #: 5561008

Change Title: System Upgrade Hot Swap Backplane to Firmware Version 2.11

Type of Notification: Class 2 Form/Fit/Function Notification

Key Characteristics of the Change:

Software

Forecasted Key Milestones:

Date of First Availability of Post-Conversion Material: June 1998

Description of Change to the Customer: This is the system level incorporation of board conversion #5563218. To improve reliability of the hot swap backplane (HSBP), firmware version 2.11 will be incorporated into system products. The new firmware resolves an issue where, under certain conditions, Mylex RAID controller cards mark hard disk drives as off-line under Windows NT 3.51 Server/Japanese.

Customer Impact of Change and Recommended Action: None.

Technical Advisory #0041 was written for this issue: Intel Customer Support (1-800-628-8686), or your Intel Sales Representative.

Test reports and plans are available for this change: Intel Customer Support (1-800-628-8686), or your Intel Sales Representative.

Firmware version 1.12/2.11, the associated update executable, and release notes are available for download on Intel's public site: <ftp://download.intel.com/design/servers/docs/fw30.zip>

Products Affected / Intel's Ordering Codes:

86505M0

86506MM

ALPC0MB2CPMC

ALPCD2001MC

ALPCD200512C

ALPCD200512C0F

ALRK0MB2CPMC

ALRK128M2X512

SERVERHX

Change Notification #: 5566881

Change Title: Upgrade CD-ROM Drive to a Faster Model

Type of Notification: Class 2 Form/Fit/Function Notification

Key Characteristics of the Change:

Product Material

Forecasted Key Milestones:

Date of First Availability of Post-Conversion Material: February 1998

Description of Change to the Customer: This change will replace the current CD-ROM drive with one capable of 24x operation.

Customer Impact of Change and Recommended Action: None.

Products Affected / Intel's Ordering Codes:

86505M0

86506MM

ALPC0MB2CPMC

ALPCD2001MC

ALPCD200512C

ALPCD200512C0F

ALRK0MB2CPMC

ALRK128M2X512

SERVERHX

3.3 AR450GX MP Rack Mount Server System

Change Notification #: 5571061

Change Title: Various Rack System Components and Boards

Type of Notification: Class 1 Form/Fit/Function Notification

Key Characteristics of the Change:

Product Material

Product Design

Forecasted Key Milestones:

Date of First Availability of Post-Conversion Material: April 1998

Description of Change to the Customer: This conversion was reported as ALRK001 in the January Monthly Conversion summary. The current metal bezel on the face of the unit will be replaced by a snap-on plastic bezel with a metal screen. An upgraded power supply (Revision J) will also be incorporated into the system.

Customer Impact of Change and Recommended Action: None.

Products Affected / Intel's Ordering Codes:

Affected Product Code	Pre-conversion subassembly/ TA#	Post-conversion subassembly/ TA#
ALRK0MB2CPMC	688084-002	688084-003
ALRK128M2X512	688084-002	688084-003

3.4 AP450GX & AR450GX Class 3 Changes

Note:

Class 3 changes are being added to the Monthly Change Summary for informational purposes. These are changes that do not affect form, fit or function of a product. These changes will not impact customers manufacturing process and/or their application. Customer notification is not required, however, Intel is providing these changes for your information. For class 3 changes, advanced notification is not generally provided.

SECTION 4: PRODUCT REVISION HISTORY

Note: Unless otherwise noted, only standard products are listed in the tables that follow. For custom product information, please contact your Intel Field Sales Representative.

4.1 Baseboard

Product	PBA	Rev.	Released BIOS Level	Released SCU	Suggested BIOS/SCU	Product Release Date	Release Notes
PALBBRD (<i>obsolete</i>)	647195	-403	1.00.04.CD0	3.40/OVL 1.31	Latest released BIOS and SCU	6/96	Fab 3.5 Production release
		-423	1.00.04.CD0	3.40/OVL 1.31	Latest released BIOS and SCU	7/96	Change manufacturing location for the B0 450GX PCiset. Replace BX flash device with a BV flash device
		-424	1.00.05.CD0	3.50/OVL 1.4	Latest released BIOS and SCU	8/96	BIOS to 1.00.05
		-425	1.00.05.CD0	3.50/OVL 1.4	Latest released BIOS and SCU	10/96	Conversion of Altera PLD's to Lattice PLD's.
		-426	1.00.05.CD0	3.50/OVL 1.4	Latest released BIOS and SCU	10/96	Conversion of high speed connector
		-428	1.00.05.CD0	3.61/OVL 1.50	Latest released BIOS and SCU	2/97	Customer specific BOM only
		-429	1.00.05.CD0	3.61/OVL 1.50	Latest released BIOS and SCU	2/97	Series resistors going to VRAM were changed
PALBBRDC	666107	-001	1.00.06.CD0	3.50/OVL 1.4	Latest released BIOS and SCU	12/96	Fab 3.5-C0 Production Release
		-002	1.00.06.CD0	3.50/OVL 1.4	Latest released BIOS and SCU	2/97	Conversion of Altera PLD's to Lattice PLD's.
		-003	1.00.08.CD0	3.61/OVL 1.50	Latest released BIOS and SCU	2/97	BIOS went to 1.00.08CD0. No boards were built or shipped.
		-004	1.00.08.CD0	3.61/OVL 1.50	Latest released BIOS and SCU	2/97	Reworked -001 board that contains Altera PLD's and the INCA anomaly fix.
		-005	1.00.08.CD0	3.61/OVL 1.50	Latest released BIOS and SCU	2/97	New board that contains Lattice PLD's and the INCA anomaly fix.
		-006	1.00.08.DC0	3.61/OVL 1.50	Latest released BIOS and SCU	2/97	Reworked -002 board that contains Lattice PLD's and the INCA anomaly fix.
		-107	1.00.08.CD0	3.61/OVL 1.50	Latest released BIOS and SCU	2/97	Changed series resistors to VRAM to improve signal quality. Added an alternate EISA connector. Changed to silkscreen to add UI marking and glue mark.
		-108	1.00.08.CD0	3.61/OVL 1.50	Latest released BIOS and SCU	5/97	Removed RTC socket for cost reduction. Added new shrouded feature connector for DPM improvement.

4.2 Modules

Product	PBA	Rev.	Product Release Date	Release Notes
Fab 3.x 512KB Processor Module (Only supports the 166/512KB Pentium® Pro Processor)				
PALCPU0X <i>(obsolete)</i>	647428	-107	6/96	Fab 3.1 Production Release
		-108	7/96	New processor socket w/stronger heat sink clip tabs
Fab 4.x 512 KB Processor Module (Supports the 166/512KB and 200/512KB Pentium® Pro processors)				
PALCPU0XA <i>(obsolete)</i> PALCPA2X166512 <i>(obsolete)</i>	659506	-212	7/96	Fab 4.1 Production Release (includes new processor socket)
		-213	9/96	Fab 4.2 New Fab which increased the clearance of nonplated holes
		-214	10/96	Altera PLD conversion to Lattice PLD
		-215	11/96	0.1µf capacitor conversion
		-216	1/97	Wire modifications made to correct the power up issue with the sB1 stepping of the Pentium® Pro processor.
		-316	2/97	Fab 4.3 New Fab to correct the power-up issue with the sB1 stepping of the Pentium® Pro Processor
		-317	8/97	Uses screened Murata capacitors in critical locations to improve board reliability
Fab 2.x 1 MB Processor Module (Supports the 166/512KB, 200/512KB and 200/1MB Pentium® Pro processors)				
PALCPA0X PALCPA2X2001M PALCPA1X200512 PALCPA2X200512	656631	-224	4/97	Fab 2.2 Production Release
		-225	6/97	A modification to the over voltage protection circuitry to prevent the circuit from Latching and turning off the DC-DC converter during a quick power on/off Situation.
		-226	8/97	Use screened capacitors in critical locations to improve board reliability.
		-303	2/98	Added protection circuitry to ensure failsafe operation.

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Product	PBA	Rev.	Product Release Date	Release Notes
2 GB Memory Module (Tin SIMM connectors and non-fused tantalum capacitors)				
PALMEM1GBM0	632487	-401	6/96	Fab 3.5 Production Release
		-402	7/96	Don't clinch stiffeners (prevents possible Vcc-GND short)
		-403	7/96	Rework -401 boards to prevent possible Vcc-GND short
		-423	7/96	Change manufacturing location for the B0 450GX PCIset.
		-424	11/96	Fab 3.6 New board Fab allowing proper crimping of stiffener pins (eliminate Vcc-GND short Issue)
		-525	8/97	New board with recessed gold fingers
2 GB Memory Module (Gold SIMM connectors and fused tantalum capacitors)				
PALMEM1GBM0TG	652238	-401	6/96	Fab 3.5 Production Release
		-402	7/96	Don't clinch stiffeners (prevents possible Vcc-GND short)
		-403	7/96	Rework -401 boards to prevent possible Vcc-GND short
		-423	7/96	Change manufacturing location for B0 450GX PCIset
		-424	8/96	Fab 3.6 New board Fab allowing proper crimping of stiffener pins (eliminate Vcc-GND short Issue)
		-525	8/97	New board with recessed gold fingers
4 GB Memory Module (DIMM connectors)				
ALMEM4GBM0	651665	-001	11/96	Production Release

Termination Module (Fab 3.1)				
PALTRMBRD	648441	-106	6/96	Fab 3.1 Production Release
		-207	8/97	Fab 3.2 The termination module will be changed to include recessed gold fingers to improve Connectivity

4.3 Chassis/System Components

Component	TA	Rev.	Product Release Date	Release Notes
Chassis Frame	636535	-010	7/96	Production Release
		-011	8/96	Mar resistant paint
		-012	11/96	Changed bolt fasteners to rivet
		-013	3/97	Drawing changes including opening tolerances. A part change involved modifying the corner, radius, and bend relief to improve hard tooling capability.
		-014	3/97	Replace existing 3x2 hard drive unit brackets & replace 5.25" drive bay.
		-015	2/98	Spatter coat paint
Pedestal Power Supply PPS420W <i>(obsolete)</i> PPS420WHS	638179	-008	7/96	Production Release
		-010	7/96	Prevent potential safety hazard (-009 was not created)
		-011	3/97	Decreased ripple, tighter regulation on -12V output, and added hot-swap feature
Rack Power Supply ALRKPS625W	690918	-001	10/97	Single 625W rack power supply
Padded Hard Drive Carrier ALPCPADHDDCAR	698443	-001	12/97	Supports 7200 and 10K RPM drives
Power Dist. Backplane	638540	-404	7/96	Production Release
		-502	3/97	Production Release
SCSI Backplane (SCA-1 Connector) <i>(obsolete)</i>	650536	-103	7/96	Production Release (Rev 1.05 Firmware)
		-104	7/97	Production Release (Rev 2.10 Firmware)
SCSI Backplane (SCA-2 Connector) POCASCIBP	685137	-001	9/97	Production Release (Rev 2.10 Firmware)
		-002	2/98	Rev 2.11 Firmware
Front Panel POCAFRONTPNL	648616	-006	7/96	Production Release (Rev 1.02 Firmware)
		-007	7/97	Rev 1.07 Firmware
		-008	8/97	Rev 1.07 Firmware
Front Bezel	636546	-004	7/96	
		-005	9/96	Production Release
		-006	10/97	Shortened hinge pin
LED Board	644025	-002	7/96	
POCALEBD		-003	8/96	Radius Corners
		-004	8/96	Production Release
Country Kit	648655	-005	7/96	Production Release

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Component	TA	Rev.	Product Release Date	Release Notes
		-006	11/96	Incorporated new 3.5/OVL 1.40 SCU, PCDIAGS 3.40, EZ-SCSI 4.00E, NW/NT/OS2/SCO/UNIX/WN driver 1.30
		-007	1/97	Incorporated new 3.61/OVL 1.50 SCU, PCDIAGS v3.42, LANDesk® 2.52a, IDE CD-ROM driver, new installation guide (Intel part #642976-003)
		-008	7/97	Incorporates 1MB addendum to the manual and Hitachi CD-ROM drivers.

4.4 Systems

Product	TA	Rev.	Product Release Date	Release Notes
Pedestal Systems				
ALPCA166512BO <i>(obsolete)</i>	654372	-001	7/96	Production Release w/BIOS 1.00.04
		-002	7/96	New Power Supply (in 8/96 upgraded to BIOS 1.00.05.CD0 w/no change to the part #)
		-003	10/96	New Processor Module(Fab 4) that allows for 200MHZ processors
		-004	11/96	New Country Kit with 3.5/OVL 1.40 SCU, PCDIAGS 3.40, EZ-SCSI 4.00E, NW/NT/OS2/SCO/UNIX/WN driver 1.30
ALPC0MB2CPB0 <i>(obsolete)</i>	660349	-001	8/96	Production Release w/BIOS 1.00.05
		-002	9/96	New Processor Module that increases clearances on non-plated holes
		-003	11/96	New Country Kit with 3.5/OVL 1.40 SCU, PCDIAGS 3.40, EZ-SCSI 4.00E, NW/NT/OS2/SCO/UNIX/WN driver 1.30
ALPCD166512BO <i>(obsolete)</i>	660350	-001	10/96	Production Release w/BIOS 1.00.05
		-002	11/96	New Country Kit with 3.5/OVL 1.40 SCU, PCDIAGS 3.40, EZ-SCSI 4.00E, NW/NT/OS2/SCO/UNIX/WN driver 1.30
ALPCD200512BO <i>(obsolete)</i>	660351	-001	10/96	Production Release w/BIOS 1.00.05
		-002	11/96	New Country Kit with 3.5/OVL 1.40 SCU, PCDIAGS 3.40, EZ-SCSI 4.00E, NW/NT/OS2/SCO/UNIX/WN driver 1.30
ALPC0MB2CPC <i>(obsolete)</i>	664941	-001	12/96	Production Release with BIOS 1.00.06 and C0 baseboard, 0 processors, 2 processor modules, 0 MB memory, 2 power supplies, 1 floppy drive
		-002	2/97	BIOS 1.00.08, -004/-005/ or -006 baseboard, -316 processor module
		-003		Added hot swap power supply and ultra SCSI capability
		-004	8/97	BIOS 1.00.12, 3.5, 1.44M
		-005	10/97	Soldered RTC instead of socketed
ALPCD166512C <i>(obsolete)</i>	664942	-001	1/97	Production Release with BIOS 1.00.06 and C0 baseboard, 2 processors (166 MHz/512KB), 1 processor module, 0 MB memory, 1 terminator module, and 2 power supplies
		-102	2/97	BIOS 1.00.08, -004/-005/ or -006 baseboard, 8x IDE CD-ROM and cable, -316 processor module
		-103	2/97	Added hot swap power supply and ultra SCSI capability
		-104	8/97	16x IDE CD-ROM
		-105	10/97	Soldered RTC instead of socketed
ALPCD200512C	664943	-001	1/97	Production Release with BIOS 1.00.06 and C0 baseboard, 2 processors (200 MHz/512 KB), 1 processor module, 0 MB memory, 1 terminator module, 2 power supplies, and 1 floppy drive
		-102	2/97	BIOS 1.00.08, -004/-005/ or -006 baseboard, 8x IDE CD-ROM and cable, -316 processor module
		-103	8/97	Added hot swap power supply and ultra SCSI capability
		-104	8/97	16x IDE CD-ROM
		-105	10/97	Soldered RTC instead of socketed
		-106	12/97	TEAC 8xxx floppy, BIOS 1.00.14.CD0, updated front panel (648616-008)
		-107		
ALPCD2001MC	676382	-001	8/97	Initial release with two 200MHz/1MB L2 processors

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Product	TA	Rev.	Product Release Date	Release Notes
		-002	7/97	
		-003	8/97	16x IDE CD-ROM
		-004	10/97	Soldered RTC instead of socketed
		-005	12/97	New power distribution backplane (638540-502), TEAC 8xxx floppy, BIOS 1.00.14.CD0, updated front panel (648616-008)
ALPC0MB2CPMC	676379	-001	8/97	Unstuffed 200MHz/1MB L2 processor capable system
		-002		
		-003	8/97	Country kit
		-004	11/97	Soldered RTC instead of socketed
		-005	12/97	New power distribution backplane (638540-502), TEAC 8xxx floppy, BIOS 1.00.14.CD0, updated front panel (648616-008)
Rack Systems				
ALRK0MB2CPMC	688098	-001	10/97	Production approved with unstuffed 200MHz/1MB L2 processor capable system, baseboard 666107-105/-107, processor module 656631-225/-226, front panel 648616-006, hot swap backplane 650536-104, memory board 652238-424/-525, hd led board 644025-003, country kit 688460-002, 16X CDROM, BIOS 1.00.12.CD0
		-002	12/97	Unstuffed 200MHz/1MB L2 processor capable system, baseboard 666107-108, processor module 656631-226, front panel 648616-007/-008, hot swap backplane 685137-001, memory board 652238-525, hd led board 644025-004, country kit 688460-002, 16X CDROM, BIOS 1.00.14.CD0
ALRK128M2X512	688084	-001	10/97	Production approved with 2 200MHz/512 KB L2 cache Pentium® Pro processors, 128MB memory, baseboard 666107-105/-107, processor module 656631-225/-226, front panel 648616-006, hot swap backplane 650536-104, memory board 652238-424/-525, hd led board 644025-003, country kit 688460-002, 16X CDROM, BIOS 1.00.12.CD0
		-002	12/97	2 200MHz/512 KB L2 cache Pentium® Pro processors, 128MB memory, baseboard 666107-108, processor module 656631-226, front panel 648616-007/-008, hot swap backplane 685137-001, memory board 652238-525, hd led board 644025-004, country kit 688460-002, 16X CDROM, BIOS 1.00.14.CD0

SECTION 5: PRODUCT DISCONTINUANCE SUMMARY

5.1

Title	Products Affected Product Code	Last Product Discontinuance Order Date ¹	Last Product Discontinuance Shipment Date	Replacement Product
Custom system with 0 processors, 2x processor modules, 2 GB memory module with 0MB memory, 2x power supplies, floppy	SERVERHX	2/12/98	6/12/98	ALC0MB2CPMC

¹ Firm, Non-cancelable orders.